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(54) HEAT-RESISTING ADHESIVE AGENT FILM FOR PRINTED BOARD AND ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a heat-resisting adhesive agent film, capable of thermocompression bonding at a low temperature without damaging superior heat-resisting property and electrical characteristics which are proper to polyimide, and to provide its manufacturing method and applying method.

SOLUTION: This heat-resisting adhesive agent film for a printed board is composed of polyimide resin of 70-99 wt.% which has silicon unit, epoxy resin of 1-30 wt.% whose epoxy equivalent is at most 500, and epoxy resin hardener. The film is inserted in a part between members to be bonded, and is used by thermocompression bonding under the conditions where the pressure is 1-100 kg/cm² and the temperature is 20-250°C.

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